

## Virtual Workshop Series on Semiconductor R&D: Workshop 4 – Advanced Packaging for Energy Efficient Microelectronics

*Hosted by the DOE/EERE Advanced Manufacturing Office (AMO)  
with the National Institute of Standards and Technology (NIST)*  
January 12-13, 2022

### DRAFT AGENDA

DAY 1: January 12, 12:30 PM – 3:00 PM EDT	
Time	Activity
12:30 – 1:50	<b>Opening Plenary</b>
12:30 – 12:45	Welcome from DOE AMO Organizer (Tina Kaarsberg, DOE AMO, Workshop Chair)
12:45 – 12:55	Opening Remarks (Becca Jones-Albertus, Acting Director, DOE AMO)
12:55 – 1:25	Keynote Talk (Bahgat Sammakia, Distinguished Professor, Binghamton University)
1:25 – 1:40	<b>BREAK</b>
1:40 – 2:40	<b>Panel on Thermal Management for 3D Microelectronics</b>
1:40 – 2:10	<ul style="list-style-type: none"> <li>- Muhannad Bakir, Georgia Institute of Technology</li> <li>- Mike Kelly, Amkor</li> <li>- Ravi Mahajan, Intel</li> <li>- Ganesh Subbarayan, Purdue University</li> </ul>
2:10 – 2:40	Panel Q&A on Thermal Management for 3D Microelectronics
2:40 – 3:00	<b>Day 1 Concluding Remarks (Tina Kaarsberg, DOE AMO, Workshop Chair)</b>

DAY 2: January 13, 12:30 PM – 3:15 PM EDT	
Time	Activity
12:30 – 12:55	<b>Opening Plenary</b>
12:30 – 12:45	Welcome Back (Tina Kaarsberg, DOE AMO, Workshop Chair)
12:45 – 12:55	Opening Remarks (NIST)
12:55 – 1:55	<b>Panel on Metrology for 3D Microelectronics</b>
12:55 – 1:25	<ul style="list-style-type: none"> <li>- Shankar Devasenathipathy, Intel</li> <li>- Will Harris, Zeiss</li> <li>- Ken Joyce, Brewer Science</li> <li>- To be announced soon</li> </ul>
1:25 – 1:55	Panel Q&A on Metrology for 3D Microelectronics
1:55 – 2:05	<b>BREAK</b>
2:05 – 3:05	<b>Panel on I/O and Interconnects for 3D Microelectronics</b>
2:05 – 2:35	<ul style="list-style-type: none"> <li>- Henning Braunisch, Intel</li> <li>- Suresh Ramalingam, Xilinx</li> <li>- Raja Swaminathan, AMD</li> <li>- Jie Xue, Cisco Systems</li> </ul>
2:35 – 3:05	Panel Q&A on I/O and Interconnects for 3D Microelectronics
3:05 – 3:15	<b>Webinar Concluding Remarks (Tina Kaarsberg, DOE AMO, Workshop Chair)</b>